



March 2014

# D45H8 / NZT45H8 PNP Power Amplifier

## Description

This device is designed for power amplifier, regulator, and switching circuits where speed is important. Sourced from process 5Q.

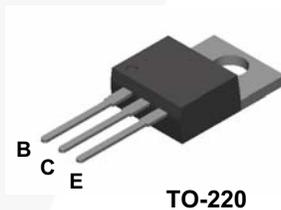


Figure 1. D45H8 Device Package

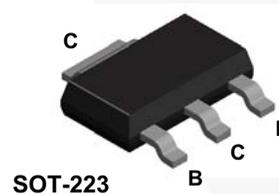


Figure 2. NZT45H8 Device Package

## Ordering Information

Part Number	Marking	Package	Packing Method
D45H8	D45H8	TO-220 3L	Rail
NZT45H8	45H8	SOT-223 4L	Tape and Reel

## Absolute Maximum Ratings<sup>(1),(2)</sup>

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only. Values are at  $T_A = 25^\circ\text{C}$  unless otherwise noted.

Symbol	Parameter	Value	Unit
$V_{CEO}$	Collector-Emitter Voltage	-60	V
$I_C$	Collector Current - Continuous	-8	mA
$T_J, T_{STG}$	Operating and Storage Junction Temperature Range	-55 to +150	$^\circ\text{C}$

### Notes:

1. These ratings are based on a maximum junction temperature of  $150^\circ\text{C}$ .
2. These are steady-state limits. Fairchild Semiconductor should be consulted on applications involving pulsed or low-duty-cycle operations.

### Thermal Characteristics<sup>(3)</sup>

Values are at  $T_A = 25^\circ\text{C}$  unless otherwise noted.

Symbol	Parameter	Max.		Unit
		D45H8	NZT45H8	
$P_D$	Total Device Dissipation	60.0	1.5	W
	Derate Above $25^\circ\text{C}$	480	12	mW/ $^\circ\text{C}$
$R_{\theta\text{JC}}$	Thermal Resistance, Junction to Case	2.1		$^\circ\text{C}/\text{W}$
$R_{\theta\text{JA}}$	Thermal Resistance, Junction to Ambient	62.5	83.3	$^\circ\text{C}/\text{W}$

#### Notes:

3. PCB size: FR-4, 76 mm x 114 mm x 1.57 mm (3.0 inch x 4.5 inch x 0.062 inch) with minimum land pattern size.

### Electrical Characteristics

Values are at  $T_A = 25^\circ\text{C}$  unless otherwise noted.

Symbol	Parameter	Conditions	Min.	Max.	Unit
$V_{(\text{BR})\text{CEO}}$	Collector-Emitter Breakdown Voltage	$I_C = -100 \text{ mA}, I_B = 0$	-60		V
$I_{\text{CBO}}$	Collector Cut-Off Current	$V_{\text{CB}} = -60 \text{ V}, I_E = 0$		-10	$\mu\text{A}$
$I_{\text{EBO}}$	Emitter Cut-Off Current	$V_{\text{EB}} = -5.0 \text{ V}, I_C = 0$		-100	$\mu\text{A}$
$h_{\text{FE}}$	DC Current Gain	$I_C = -2.0 \text{ A}, V_{\text{CE}} = -1.0 \text{ V}$	60		
		$I_C = -4.0 \text{ A}, V_{\text{CE}} = -1.0 \text{ V}$	40		
$V_{\text{CE(sat)}}$	Collector-Emitter Saturation Voltage	$I_C = -8.0 \text{ A}, I_B = -0.4 \text{ A}$		-1.0	V
$V_{\text{BE(sat)}}$	Base-Emitter Saturation Voltage	$I_C = -8.0 \text{ A}, I_B = -0.8 \text{ A}$		-1.5	V
$V_{\text{BE(on)}}$	Base-Emitter On Voltage	$I_C = -10 \text{ mA}, V_{\text{CE}} = -2.0 \text{ V}$	-0.54	-0.65	V
$f_T$	Current Gain - Bandwidth Product	$I_C = -500 \text{ mA}, V_{\text{CE}} = -10 \text{ V}, f = 100 \text{ MHz}$	40		MHz

### Typical Performance Characteristics

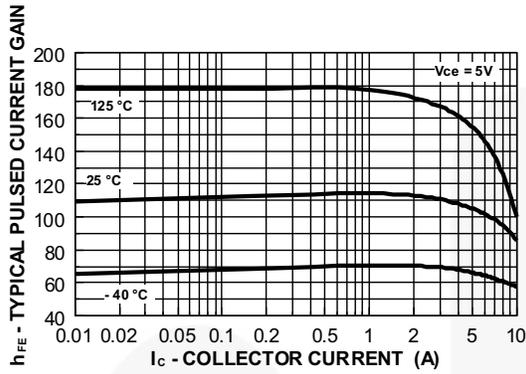


Figure 3. Typical Pulsed Current Gain vs. Collector Current

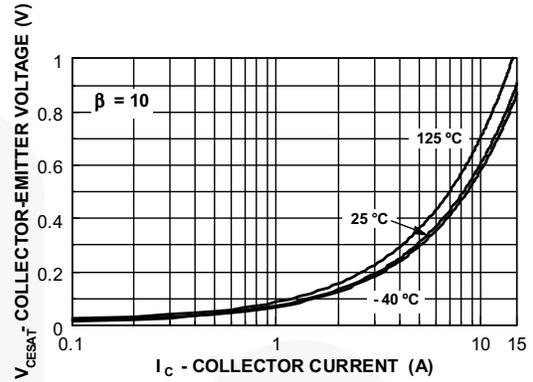


Figure 4. Collector-Emitter Saturation Voltage vs. Collector Current

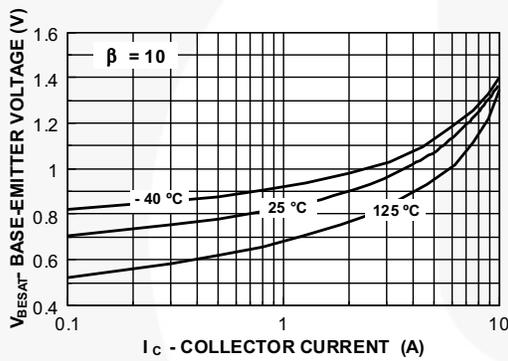


Figure 5. Base-Emitter Saturation Voltage vs. Collector Current

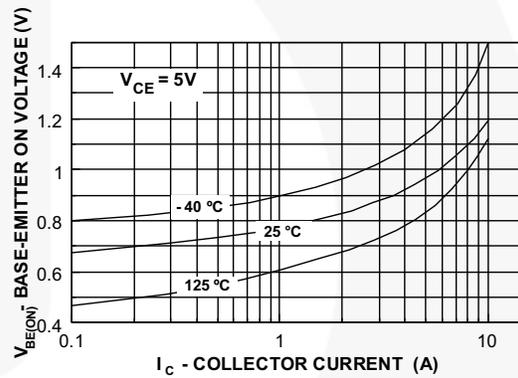


Figure 6. Base-Emitter On Voltage vs. Collector Current

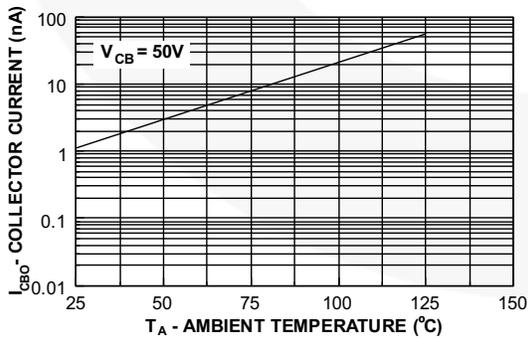


Figure 7. Collector Cut-Off Current vs. Ambient Temperature

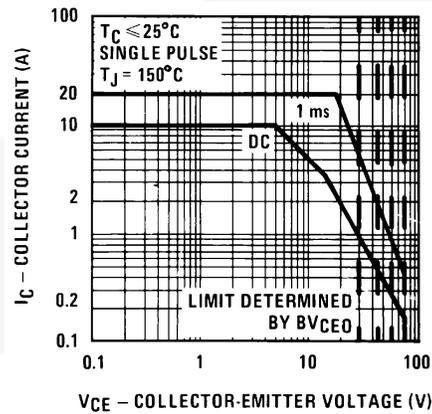


Figure 8. Safe Operating Area TO-220

Typical Performance Characteristics (Continued)

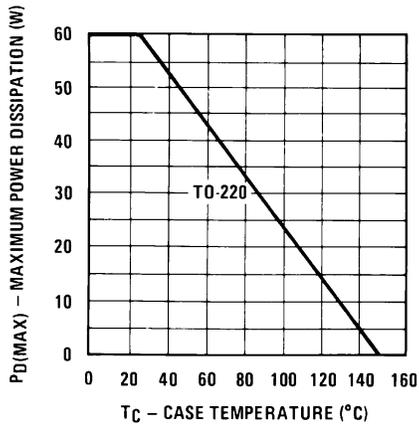


Figure 9. Maximum Power Dissipation vs. Case Temperature

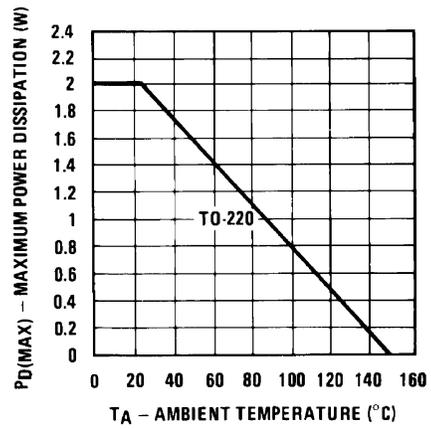


Figure 10. Maximum Power Dissipation vs. Ambient Temperature

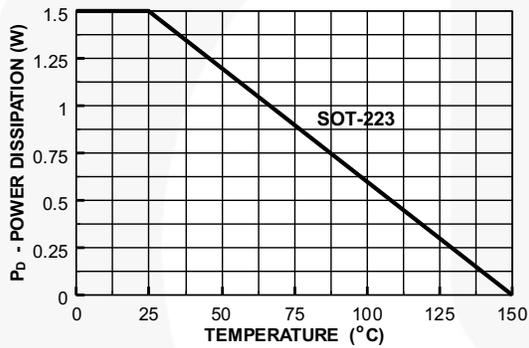


Figure 11. Power Dissipation vs. Ambient Temperature

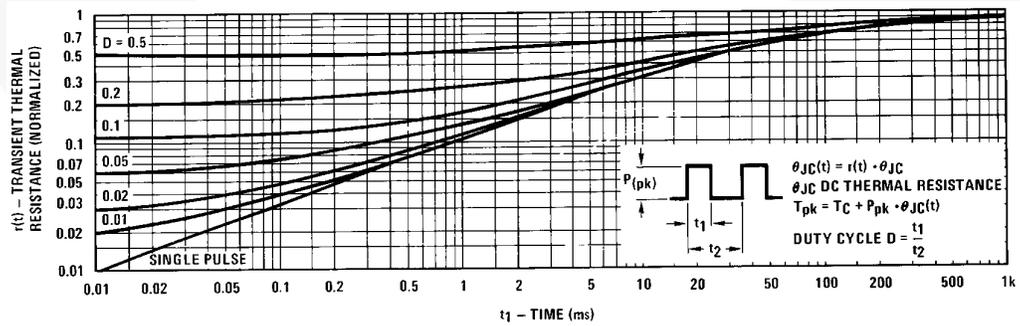
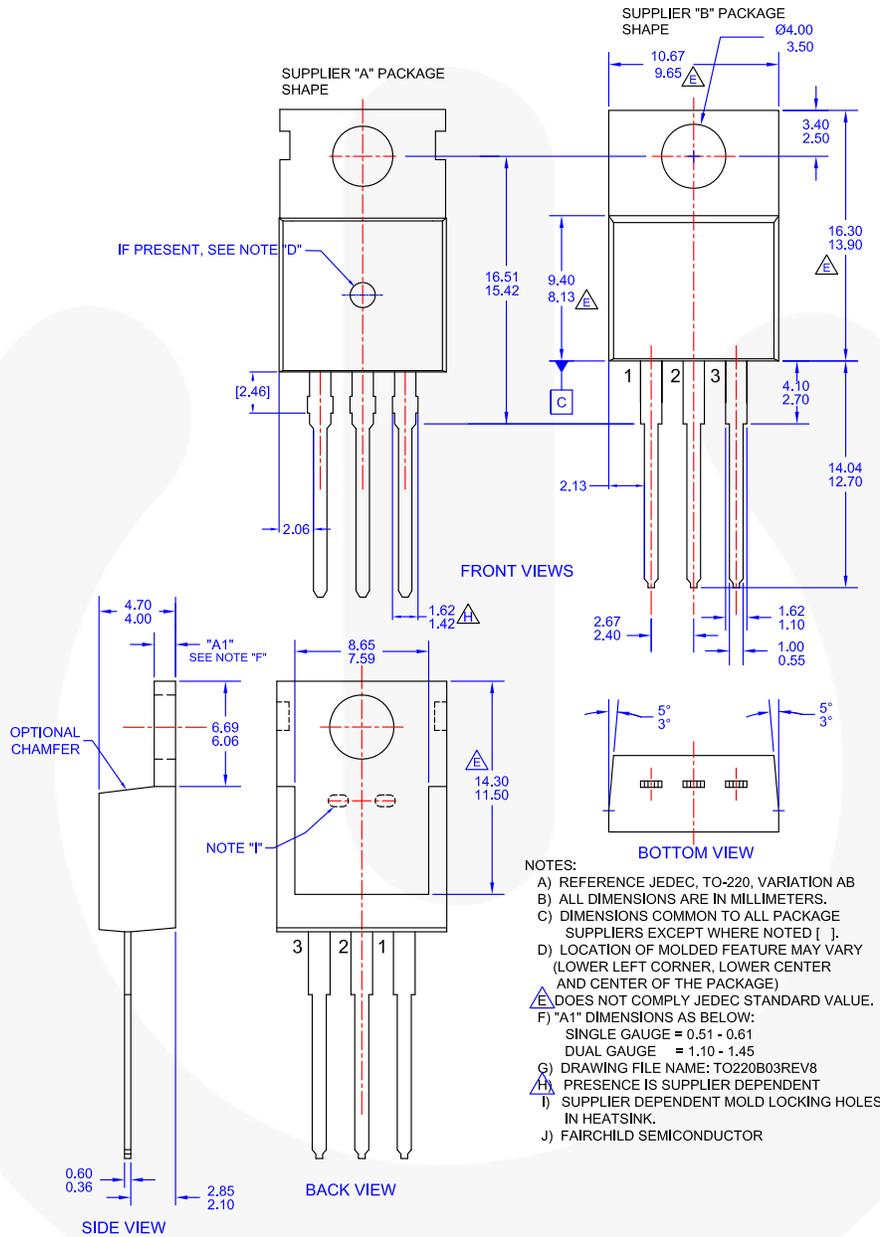


Figure 12. Thermal Response in TO-220 Package

## Physical Dimensions

### TO-220 3L



**Figure 13. TO-220, MOLDED, 3LEAD, JEDEC VARIATION AB (ACTIVE)**

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For current tape and reel specifications, visit Fairchild Semiconductor's online packaging area:

[http://www.fairchildsemi.com/packaging\\_dwg/PKG-TO220B03.pdf](http://www.fairchildsemi.com/packaging_dwg/PKG-TO220B03.pdf)

Physical Dimensions (Continued)

SOT-223

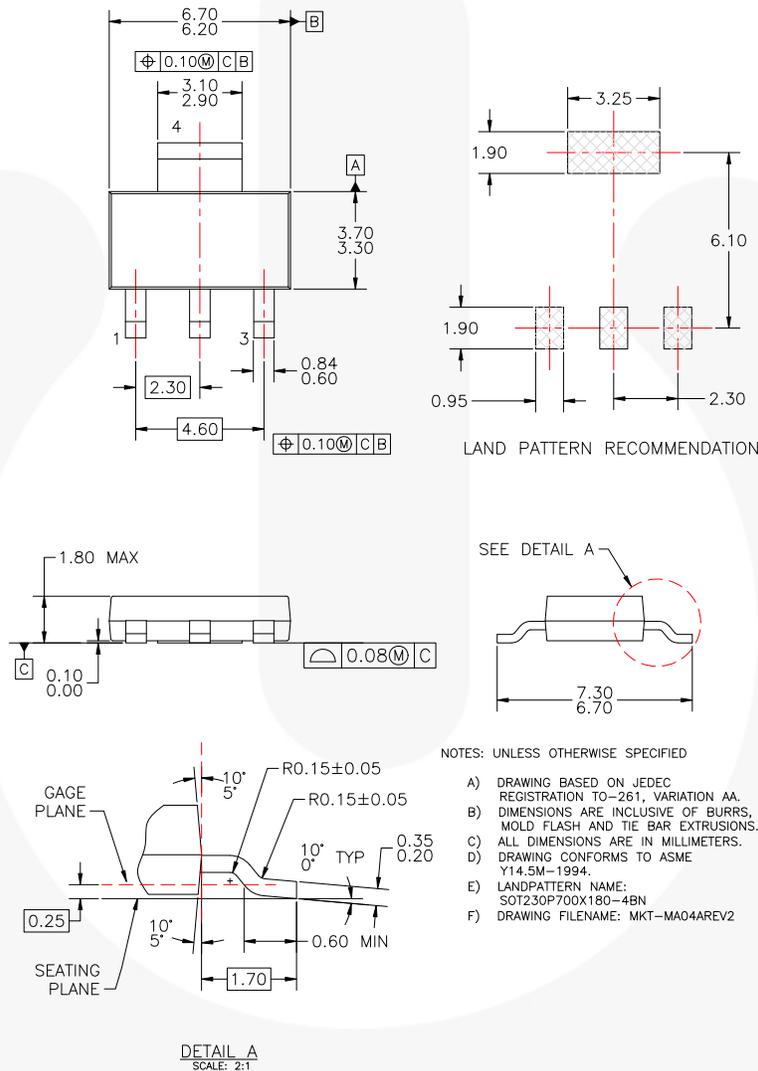


Figure 14. MOLDED PACKAGE, SOT-223, 4 LEAD (ACTIVE)

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